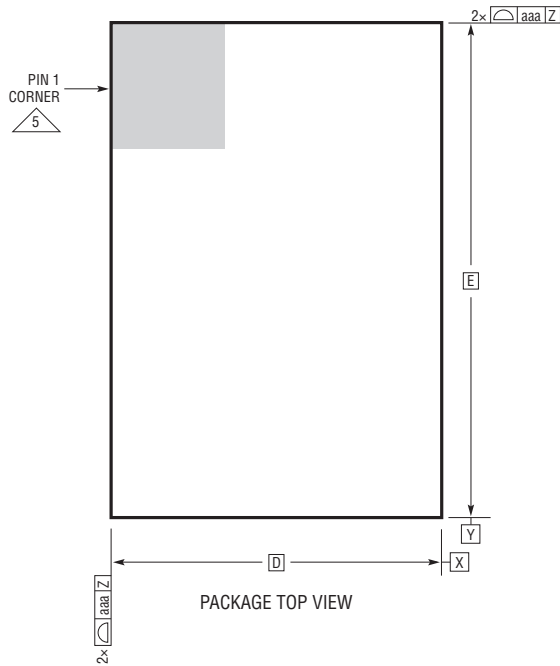
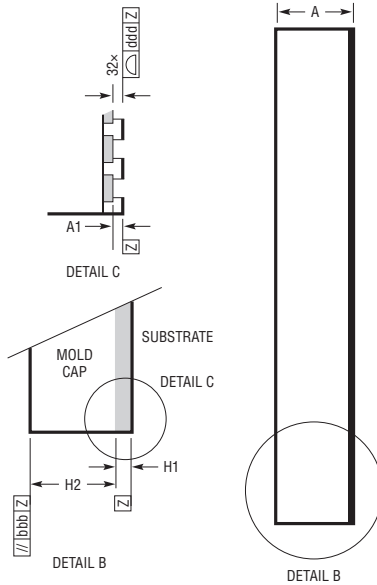


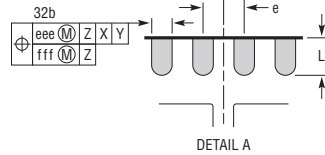
LQFN Package
32-Lead (6mm × 4mm × 0.94mm)
 (Reference LTC DWG # 05-08-1557 Rev A)



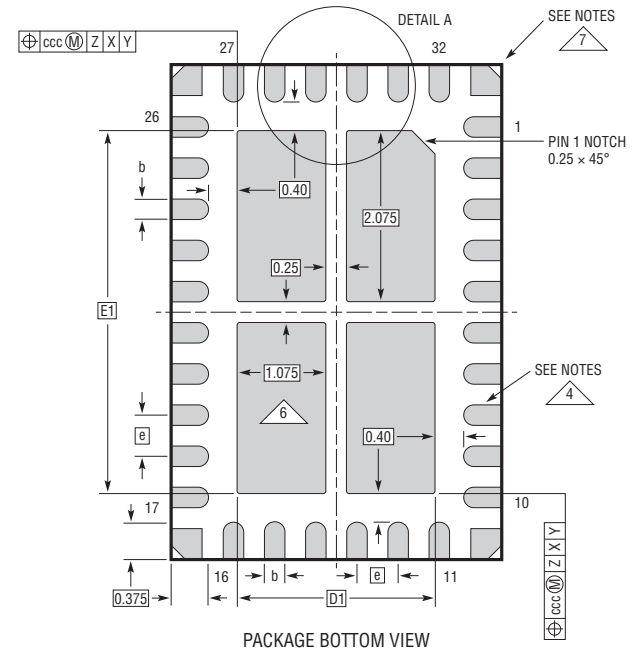
PACKAGE TOP VIEW



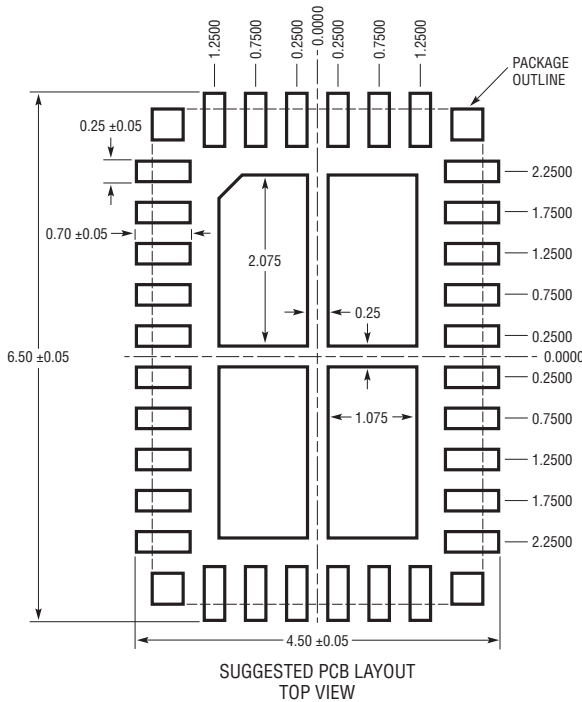
DETAIL B



DETAIL A



PACKAGE BOTTOM VIEW

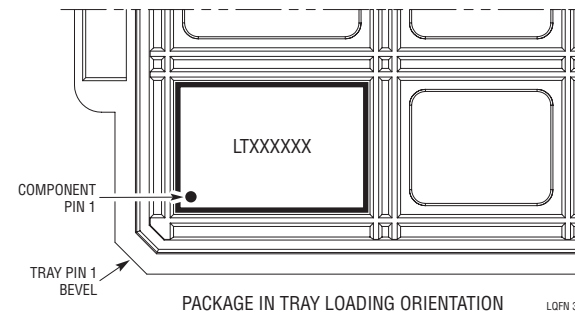


SUGGESTED PCB LAYOUT TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	0.85	0.94	1.03	
A1	0.01	0.02	0.03	
L	0.30	0.40	0.50	
b	0.22	0.25	0.28	
D		4.00		
E		6.00		
e		0.50		
D1		2.40		
E1		4.40		
H1		0.24 REF		SUBSTRATE THK
H2		0.70 REF		MOLD CAP HT
aaa			0.10	
bbb			0.10	
ccc			0.10	
ddd			0.10	
eee			0.15	
fff			0.08	

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. PRIMARY DATUM -Z- IS SEATING PLANE

4. METAL FEATURES UNDER THE SOLDER MASK OPENING NOT SHOWN SO AS NOT TO OBSCURE THESE TERMINALS AND HEAT FEATURES
5. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
6. THE EXPOSED HEAT FEATURE IS SEGMENTED AND ARRANGED IN A MATRIX FORMAT. IT MAY HAVE OPTIONAL CORNER RADII ON EACH SEGMENT
7. CORNER SUPPORT PAD CHAMFER IS OPTIONAL



PACKAGE IN TRAY LOADING ORIENTATION